



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BVDSS	Rds(on) Max	I _D Max T _A = +25°C
		$29m\Omega$ @ V _{GS} = 4.5V	5.6A
Q1	12V	$34m\Omega$ @ $V_{GS} = 2.5V$	5.1A
N-Channel	120	44mΩ @ V _{GS} = 1.8V	4.5A
		65mΩ @ V _{GS} = 1.5V	3.7A
		61mΩ @ V _{GS} = -4.5V	-3.8A
Q2	-12V	81mΩ @ V _{GS} = -2.5V	-3.3A
P-Channel	-12V	115mΩ @ V _{GS} = -1.8V	-2.8A
		170mΩ @ V _{GS} = -1.5V	-2.3A

Description

This MOSFET is designed to minimize the on-state resistance (RDS(ON)), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

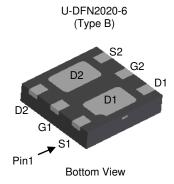
- Load Switch
- Power Management Functions
- Portable Power Adaptors

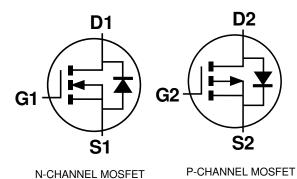
Features

- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/guality/product-definitions/

Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202. Method 208
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)





Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC1229UFDB -7	U-DFN2020-6 (Type B)	3,000/Tape & Reel
DMC1229UFDB -13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



D2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2012		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Z		Н		J	K	L	М	N	0	Р	R
								A	0	0-4	Maria	D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



D2 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020)

W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2012	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	2	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-Channel	Q2 P-Channel	Unit
Drain-Source Voltage			V _{DSS}	12	-12	V
Gate-Source Voltage			Vgss	±8	±8	V
			I _D	5.6 4.4	-3.8 -3.0	Α
Continuous Drain Current (Note 5) V _{GS} = 4.5V T _A = +25°C T _A = +70°C			ID	7.2 5.8	-5.0 -4.0	Α
Maximum Continuous Body Diode Forward Current (Note 5)			Is	1	-1	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)		I _{DM}	20	-15	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	Steady State	Do	1.4	W
Total Fower Dissipation (Note 3)	t<5s	PD	2.2	VV
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	92	
memai Resistance, Junction to Ambient (Note 5)	t<5s	$R_{\theta JA}$	55	°C/W
Thermal Resistance, Junction to Case (Note 5)		Rejc	30	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Note: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. copper, single sided.



Electrical Characteristics Q1 N-Channel (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	12	I		٧	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	l	I	1.0	μΑ	$V_{DS} = 12V$, $V_{GS} = 0V$
Gate-Source Leakage	Igss		1	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	0.4	-	1	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		_	17	29		$V_{GS} = 4.5V, I_D = 5A$
Static Drain-Source On-Resistance	Doggan	_	20	34	mΩ	$V_{GS} = 2.5V, I_{D} = 4.6A$
Static Dialii-Source Ori-nesistance	R _{DS(ON)}	l	24	44	11122	$V_{GS} = 1.8V, I_D = 4.1A$
		l	30	65		$V_{GS} = 1.5V, I_D = 2A$
Forward Transfer Admittance	Y _{fs}		6.5		s	$V_{DS} = 10V, I_{D} = 5A$
Diode Forward Voltage	V _{SD}	_	0.6	1.2	V	V _G S = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss		914		рF	V 0V V 0V
Output Capacitance	Coss	l	132	l	рF	V _{DS} = 6V, V _{GS} = 0V, -f = 1.0MHz
Reverse Transfer Capacitance	Crss		119		pF	1 - 1.0WH 12
Gate Resistance	Rg		1.26		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (VGS = 4.5V)			10.5		nC	
Total Gate Charge (V _{GS} = 8V)	Qg	_	19.6	_	nC	V _{DS} = 6V. I _D = 6.5A
Gate-Source Charge	Qgs	_	1.2	_	nC	VDS = 6V, ID = 6.5A
Gate-Drain Charge	Qgd	_	1.6	_	nC	
Turn-On Delay Time	t _{D(on)}	_	5.0	_	ns	
Turn-On Rise Time	tr	_	10.5	_	ns	$V_{DD} = 6V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(off)}	_	16.6	_	ns	$R_L = 1.2\Omega$, $R_G = 1\Omega$
Turn-Off Fall Time	tf	_	4.1	_	ns]

Electrical Characteristics Q2 P-Channel (@T_A = +25°C, unless otherwise specified.)

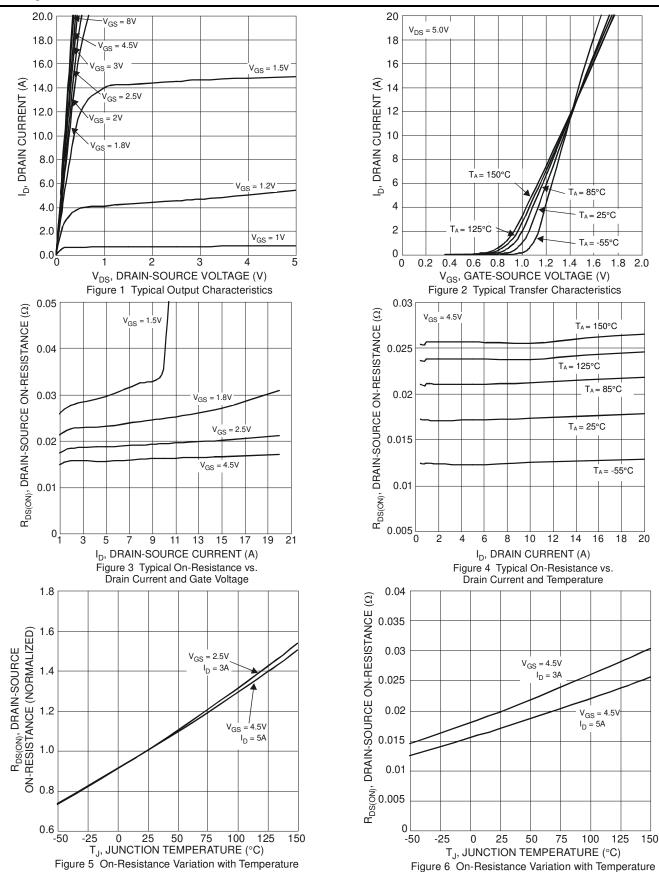
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-12	1		٧	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	-	-1.0	μΑ	$V_{DS} = -12V$, $V_{GS} = 0V$
Gate-Source Leakage	Igss	l	I	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	-	-1	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
		_	37	61		$V_{GS} = -4.5V, I_D = -3.6A$
Static Drain-Source On-Resistance	Process	_	47	81	mΩ	$V_{GS} = -2.5V$, $I_{D} = -3.2A$
Static Diani-Source On-nesistance	RDS(ON)	l	63	115	11122	$V_{GS} = -1.8V, I_{D} = -1A$
			90	170		$V_{GS} = -1.5V, I_{D} = -1A$
Forward Transfer Admittance	Y _{fs}	l	5.5		S	$V_{DS} = -10V$, $I_{D} = -3.6A$
Diode Forward Voltage	V _{SD}	_	-0.65	-1.2	٧	VGS = 0V, IS = -1A
DYNAMIC CHARACTERISTICS (Note 7)	•					
Input Capacitance	C _{iss}	_	915	_	pF	
Output Capacitance	Coss	_	225	-	pF	V _{DS} = -6V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	183	-	pF	1 - 1.0Wil 12
Gate Resistance	Rg		56.9		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (VGS = -4.5V)	0	_	10.7	_	nC	
Total Gate Charge (VGS = -8V)	Qg	_	17.9	_	nC	V CV I- 4.04
Gate-Source Charge	Qgs	_	1.7	_	nC	V _{DS} = -6V, I _D = -4.3A
Gate-Drain Charge	Q _{gd}	_	3.0	_	nC	1
Turn-On Delay Time	t _{D(on)}	_	5.7	_	ns	
Turn-On Rise Time	tr	_	11.5	_	ns	$V_{DD} = -6V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t _{D(off)}	_	27.8	_	ns	$R_L = 1.6\Omega$, $R_G = 1\Omega$
Turn-Off Fall Time	Ìf	_	26.4	_	ns	

Notes: 6. Short duration pulse test used to minimize self-heating effect.

^{7.} Guaranteed by design. Not subject to product testing.



Q1 N-CHANNEL





Q1 N-CHANNEL (continued)

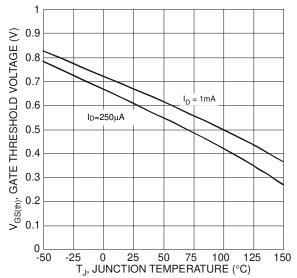
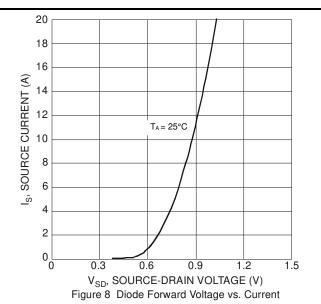
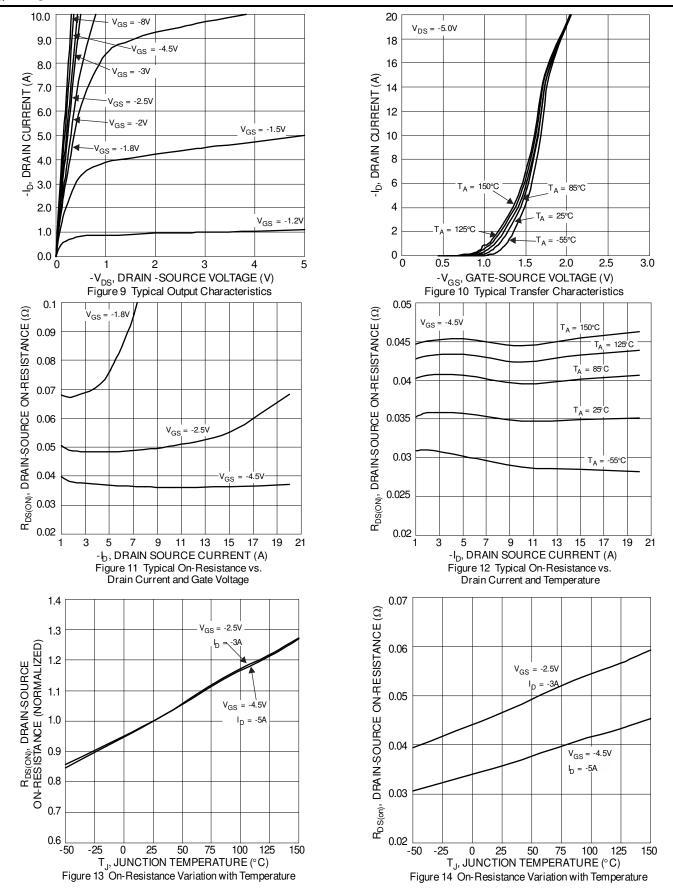


Figure 7 Gate Threshold Variation vs. Junction Temperature





Q2 P-CHANNEL





Q2 P-CHANNEL (continued)

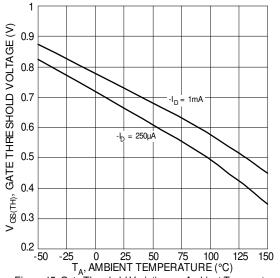
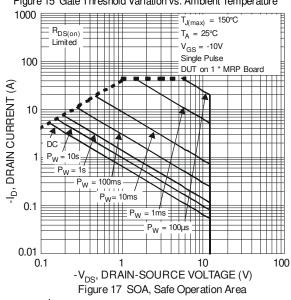
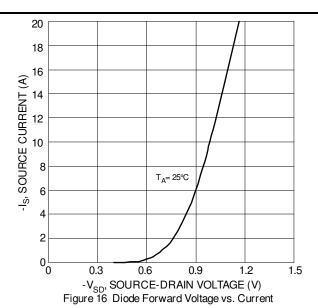
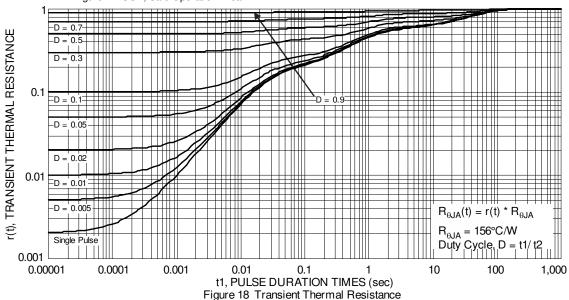


Figure 15 Gate Threshold Variation vs. Ambient Temperature





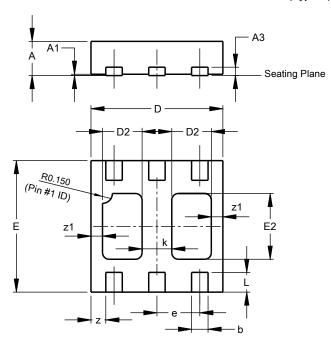




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)

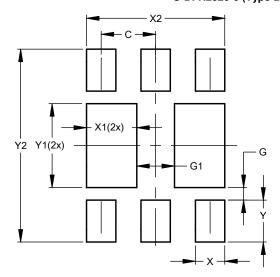


	U-DFN2020-6 (Type B)						
Dim	Min Max Typ						
Α	0.545	0.605	0.575				
A 1	0.00	0.05	0.02				
A3	-	-	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
D2	0.50	0.70	0.60				
е	-	-	0.65				
E	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
k	1	-	0.45				
L	0.25	0.35	0.30				
Z	-	-	0.225				
z1	-	-	0.175				
All	Dimens	ions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
С	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300



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